# **Specification of Thermoelectric Module**

## **TEC1-03504**

### Description

The 35 couples,  $15 \text{ mm} \times 30 \text{ mm}$  size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

#### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

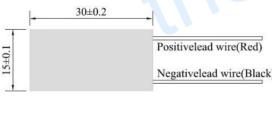
# **Performance Specification Sheet**

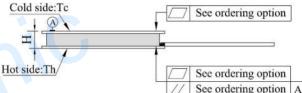
## Application

- · Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th(°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	4.5	4.8	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max(</sub> amps)	4	4	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	11.2	12.3	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	0.85	0.92	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

#### Geometric Characteristics Dimensions in millimeters





Eg. TF01: Thickness 4

Suffix

TF TF

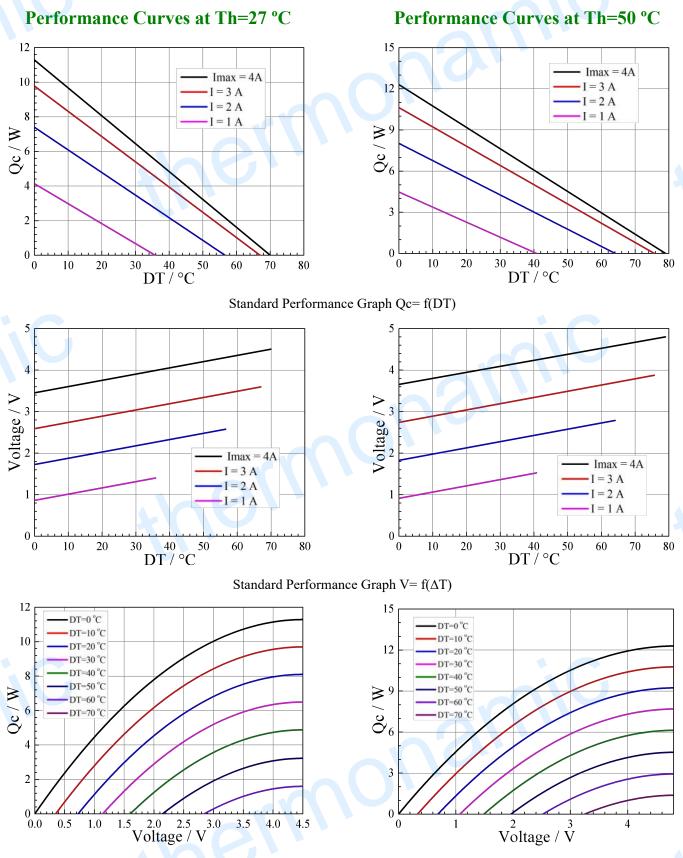
# **Manufacturing Options**

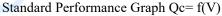
30±0.2			A. Solder:		B. Sealant:	
Positivelead wire(Red)			1. T100: BiSn (Tmelt=138°C)		1. NS: No sealing (Standard)	
Negativelead wire(Black)			2. T200: CuAgSn (Tmelt = 217°C)		2. SS: Silicone sealant	
See ordering option			3. T240: SbSn (	Tmelt = $240^{\circ}$ C)	3. EPS: Epoxy sealant	
			C. Ceramics:		D. Ceramics Surface Options:	
See ordering option // See ordering option A			1. Alumina (Al <sub>2</sub> O <sub>3</sub> , white 96%)		1. Blank ceramics (not metalized)	
			2. Aluminum Nitride (AlN)		2. Metalized	
Ord	ering Option		Naming for the Module			
Thickness	Flatness/	Lead wire l	length(mm)	TEC1-03504- X-X-X-X		
H (mm)	Parallelism (mm)	Standard/Op	tional length		Ceramics Flatness/Parallelism Sealant	
$0{:}4.0\pm0.1$	0: 0.05/0.07	150±3/	Specify			
$1{:}4.0\pm0.03$	1: 0.02/0.025	150±3/	Specify	Solder TEC1- 03504-T100 -NS -TF01 -AlO		
: Thickness $4.0 \pm 0.1$ (mm) and Flatness $0.02/0.025$ (mm)				T100: BiSn(Tmelt=138°C)		
				NS: No sealing TF01: Thickness $\pm$ 0.1	AlO: Alumina, white 96% (mm) and Flatness/Parallelism 0.1/0.13(mm)	

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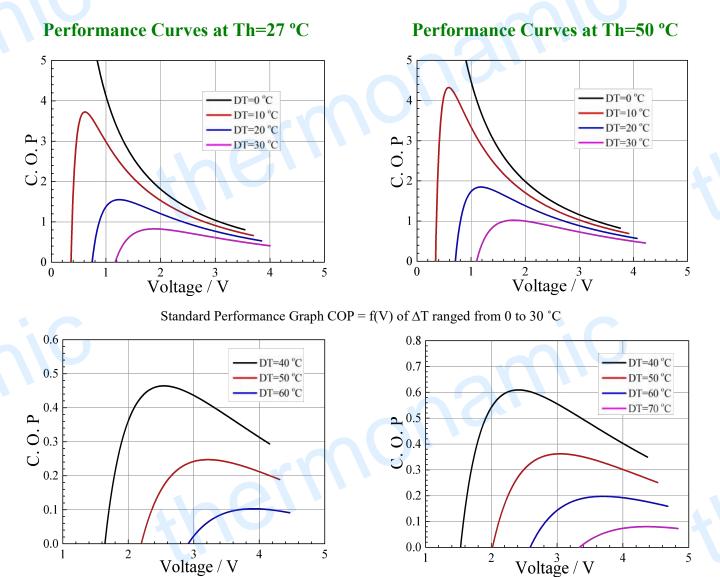
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## **Specification of Thermoelectric Module**

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Standard Performance Graph COP = f(V) of  $\Delta T$  ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power Qc/Input power ( $V \times I$ ).

### **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC

Note: All specifications subject to change without notice.